

Sputtering Disk Inspection Using UltraWin C-Scan

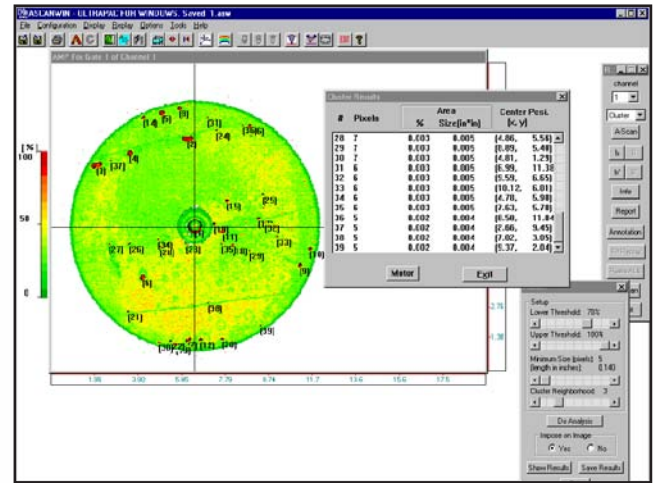
Current Condition

Sputtering deposition is widely used in the semi-conductor industry in the manufacturing of thin films and storage media. The process basically involves depositing material, under vacuum, onto a negatively charged disc known as a sputtering target. Due to the high stresses involved, it is critical that the bimetal target be thoroughly bonded to insure the production of quality films. A determination of the quality of the bond must be made in a timely, cost-effective manner.

Solution

The screen capture to the right shows an Ultrasonic C-Scan of a typical sputtering target (.480" Nickel solder bonded to .280" copper plate). The circular red areas depict voids detected in the solder bond. Further analysis with UltraWin clustering software automatically located and graded 39 voids. The Ultrasonic results were later 100% verified by mechanically peeling the nickel target from the copper substrate.

The inspection setup using an UltraPAC UT Immersion



System is shown at the left. It is a straightforward inspection using a standard focused UT immersion transducer. Data shown was obtained using a 15 MHz transducer with 2-inch focal length and the AD-IPR-1210 board.

Inspection speeds can be set to maximum allowable per the immersion system used - resulting in rapid inspection time - and a low-cost production quality validation for our customers.

MISTRAS Software & Systems division, is a team of skilled researchers, engineers, technicians and manufacturing personnel dedicated to the development on practical and cost saving solutions to your challenging inspection needs.

For a demonstration or additional information, please contact our Princeton Junction headquarters at 609-716-4000.

